



P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
-30V	$42m\Omega$ @ $V_{GS} = -10V$	-5.1A
-307	65mΩ @ V _{GS} = -4.5V	-4.0A

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power Management Functions
- **DC-DC Converters**

Mechanical Data

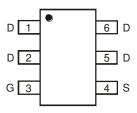
- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208@3
- Weight: 0.015 grams (Approximate)



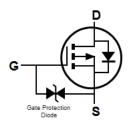


TSOT26

Top View



Top View Internal Schematic



Equivalent Circuit

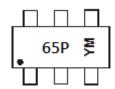
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP3065LVT-7	TSOT26	3,000/Tape & Reel
DMP3065LVT-13	TSOT26	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and -1000ppm antimony compounds.
 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



65P = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: A = $2\overline{0}13$) M = Month (ex: 9 = September)

Date Code Key

Year	2011		2012	2013		2014	2015		2016	2017		2018
Code	Υ		Z	Α		В	С		D	Е		F
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings P-Channel (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		V_{DSS}	-30	V	
Gate-Source Voltage		V _{GSS}	±20	V	
Continuous Drain Current (Note 5) $V_{GS} = -10V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$		I _D	-5.1 -4.2	А	
Continuous Drain Current (Note 5) $V_{GS} = -4.5V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$			I _D	-4.0 -3.2	Α
Maximum Body Diode Continuous Current	I _S	-2.0	Α		

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 6)		P _D	1.2	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	102	°C/W
Total Power Dissipation (Note 5)		P_{D}	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R _{0JA}	78	°C/W
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

Electrical Characteristics P-Channel (@TA = +25°C, unless otherwise specified.)

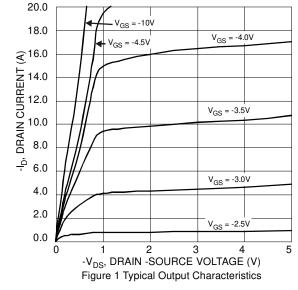
Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)								
Drain-Source Breakdown Voltage		BV _{DSS}	-30	1	1	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	$@T_J = +25^{\circ}C$	I _{DSS}		1	-1	μA	$V_{DS} = -24V$, $V_{GS} = 0V$	
Gate-Source Leakage		I _{GSS}		1	±10	μA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)								
Gate Threshold Voltage		V _{GS(th)}	-1	-1.7	-2.1	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$	
Static Drain-Source On-Resistance	ļ	Dec (a)	_	34	42	mO	$V_{GS} = -10V, I_D = -4.9A$	
Static Drain-Source On-Nesistance		R _{DS} (ON)	_	52	65	11122	$V_{GS} = -4.5V, I_D = -3.7A$	
Forward Transfer Admittance		Y _{fs}		8.5	1	S	$V_{DS} = -5V, I_D = -4.9A$	
Diode Forward Voltage		V_{SD}		-0.75	-1.2	V	$V_{GS} = 0V$, $I_S = -1A$	
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance		C _{iss}		587	880			
Output Capacitance		Coss		160	240	pF	$V_{DS} = -15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance		C _{rss}	_	84	130		= 1.0 V	
Total Gate Charge (V _{GS} = -4.5V)		Qg		6.3	10			
Total Gate Charge (V _{GS} = -10V)		Qg		12.3	20	nC	4577 1 404	
Gate-Source Charge		Qgs		1.9	4	110	$V_{DS} = -15V, I_{D} = -4.9A$	
Gate-Drain Charge		Q_{gd}		2.5	5			
Turn-On Delay Time		t _{D(on)}		5.7	10			
Turn-On Rise Time		t _r	_	11.8	22	20	$V_{DD} = -15V, V_{GS} = -10V,$	
Turn-Off Delay Time		t _{D(off)}	_	21.8	35	ns	$I_D = -4.9A, R_G = 6\Omega$	
Turn-Off Fall Time		t _f	_	23.9	40			

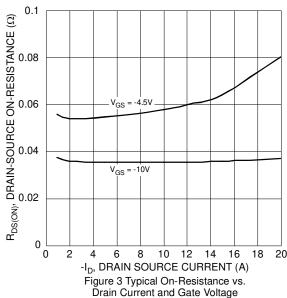
5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

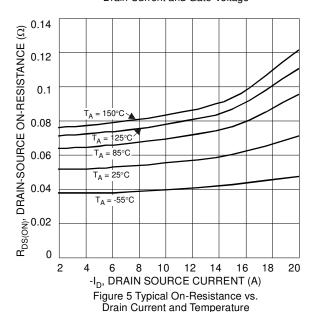
^{6.} Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 7. Short duration pulse test used to minimize self-heating effect.

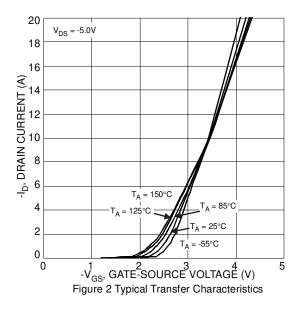
^{8.} Guaranteed by design. Not subject to product testing.

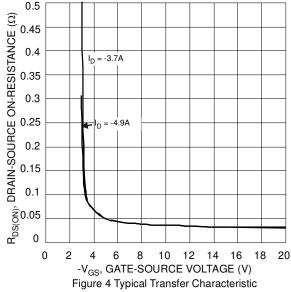


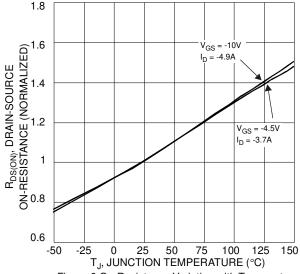














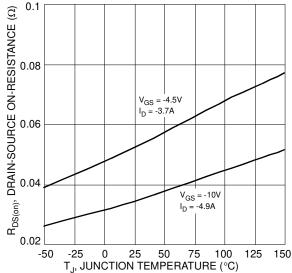
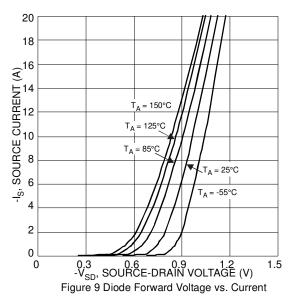
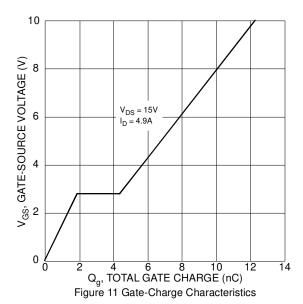


Figure 7 On-Resistance Variation with Temperature





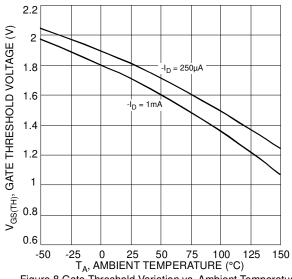
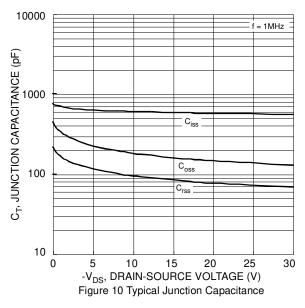
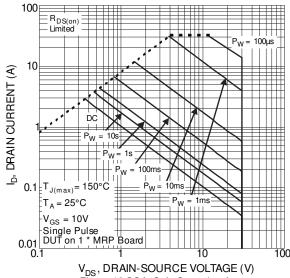


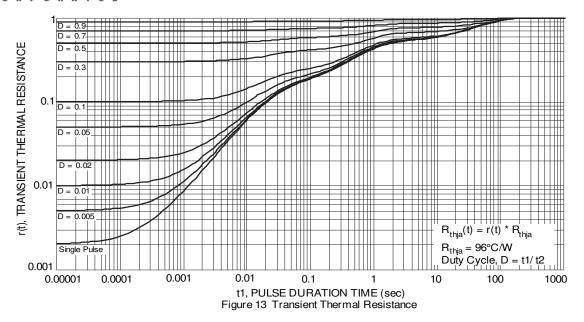
Figure 8 Gate Threshold Variation vs. Ambient Temperature





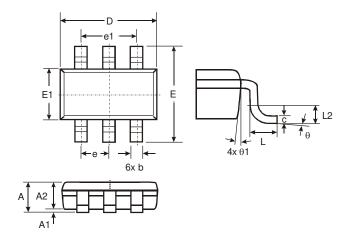
 ${
m V_{DS}}$, DRAIN-SOURCE VOLTAGE (V) Figure 12 SOA, Safe Operation Area





Package Outline Dimensions

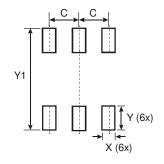
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



TSOT26								
Dim	Min	Max	Тур					
Α	ı	1.00	-					
A 1	0.01	0.10	_					
A2	0.84	0.90	-					
D	1	_	2.90					
Е		_	2.80					
E1	I	_	1.60					
q	0.30	0.45	-					
O	0.12	0.20	_					
Ф	1	_	0.95					
e1	ı	-	1.90					
L	0.30	0.50						
L2	ı	_	0.25					
θ	0°	8°	4°					
θ1	4°	12°	_					
All Dimensions in mm								

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
С	0.950			
X	0.700			
Υ	1.000			
Y1	3.199			



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